

Features

- Extreme Low Losses in Passband (typ. 0.5dB)
- High Power Durability
- High attenuations at GSM, PDC, PHS, UMTS, and WLAN Bands
- Excellent reflow solderability, no migration effect due to copper/tin metallization

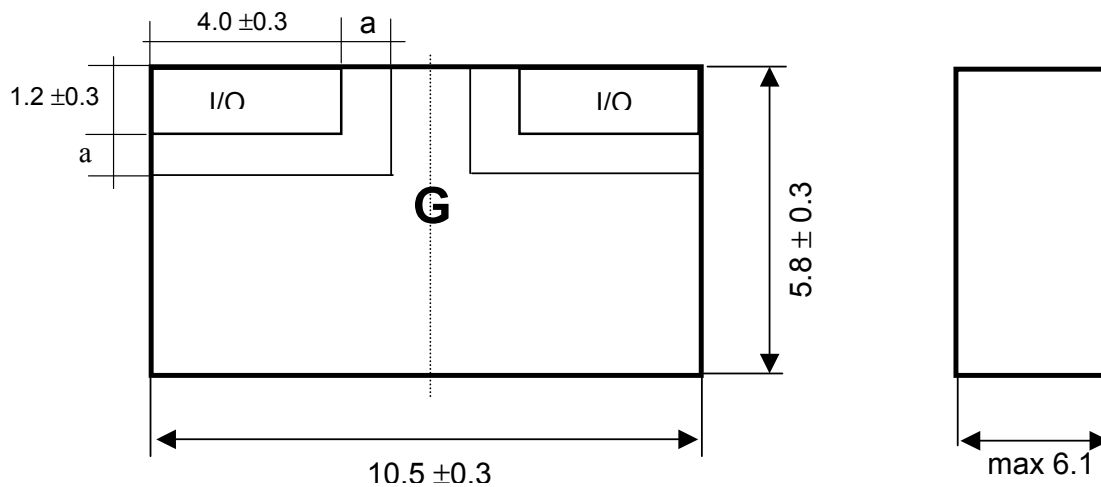
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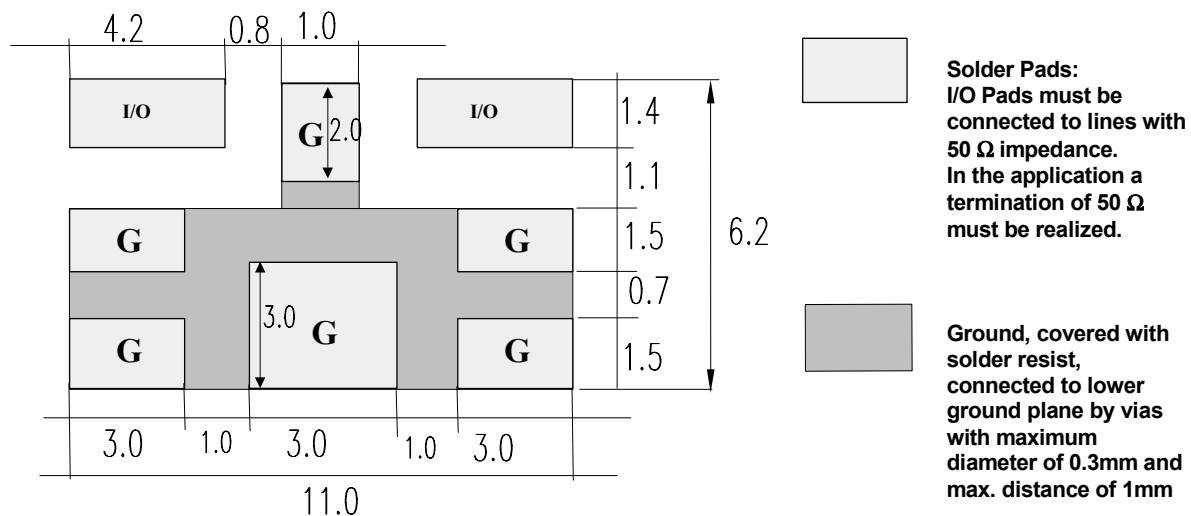
Preliminary Datasheet

Dimension Limits



$$a = 0.9 \pm 0.4$$

Recommended Footprint



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Preliminary Datasheet

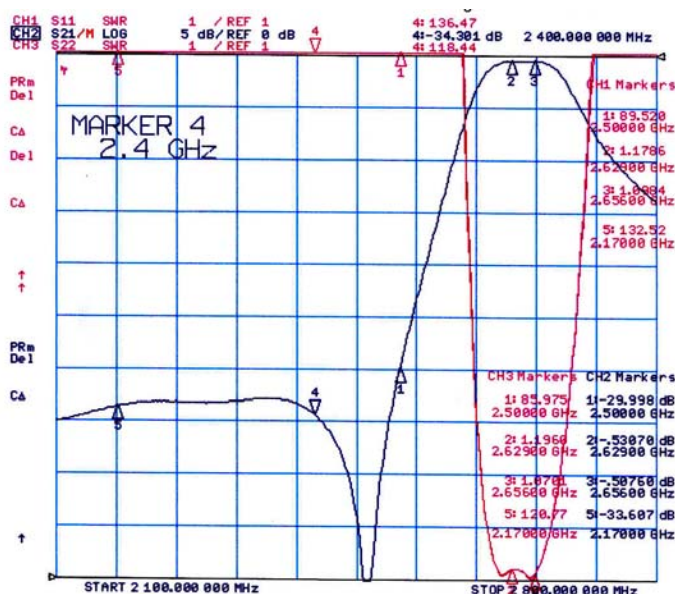
Characteristics (over whole temperature range)

		min.	typ.	max.	
Center frequency	f_c	-	2.6425	-	GHz
Insertion loss	α_{IL}		0.5	0.7	dB
Passband (2629- 2656)	B	27			MHz
Amplitude ripple (peak - peak)	$\Delta\alpha$		0.1	0.2	dB
Standing Wave Ratio / Return Loss [dB]			1.12 / -25	1.5 / -14	
Impedance	Z		50		Ω
Attenuation	α				
	at DC to 440 MHz	57	60		dB
	at 440 to 1525 MHz	40	44		dB
	at 1525 to 1680 MHz	38	41		dB
	at 1680 to 1980 MHz	34	38		dB
	at 1980 to 2170 MHz	30	33		dB
	at 2170 to 2500 MHz	27	29		dB
	at 3450 MHz	35	40		dB

Maximum ratings

IEC climatic category (IEC 68-1)		- 40 /+ 90/56	
Operating temperature	T_{op}	- 40 / + 85	°C

Typical passband characteristics

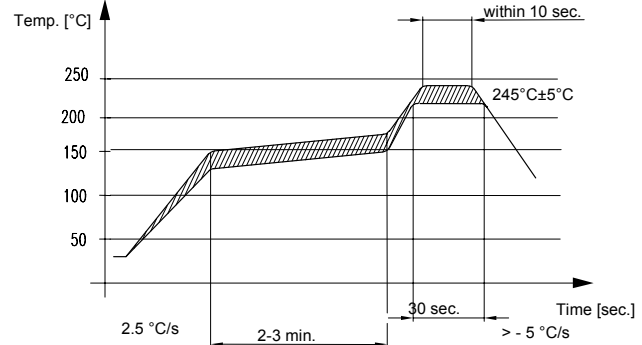
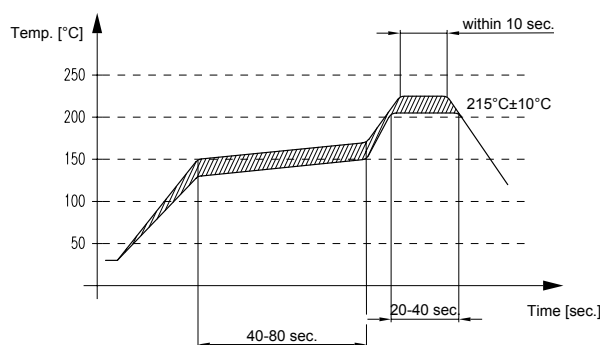


Processing information

Wettability to IEC 68-2-58: $\geq 75\%$ (after aging)

Soldering Requirements

	Profile for eutectic SnPb solder paste	Profile for leadfree solder paste	
Soldering type	reflow	reflow	
Maximum soldering temperature	235 (max. 2 sec.)	260 (max. 2 sec.)	°C
(measuring point on top surface of the component)	225 (max. 10 sec.)	250 (max. 10 sec.)	°C

Recommended soldering conditions (infrared):

Delivery mode

- Blister tape acc. to IEC 286-3, grey
- Pieces/tape: **t.b.d**

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The information contained in this data sheet describes the type of component and shall not be considered as guaranteed characteristics. Purchase orders are subject to the General Conditions for the Supply of Products and Services of the Electrical and Electronics Industry recommended by the ZVEI (German Electrical and Electronic Manufacturers' Association), unless otherwise agreed.

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